**Please complete all sections**

|  |  |  |  |
| --- | --- | --- | --- |
| **CUSTOMER:** |  | **CASE #:** |  |
| **DISTRIBUTOR:** |  | **PO / SO #** |  |

|  |  |  |  |
| --- | --- | --- | --- |
| **PART #:** |  | **DATE CODE:** |  |
| **CUST REF. #:** |  | **LOT #/ BATCH #** |  |
| **TESTED QTY:** |  | **FAILED QTY:** |  | **RETURNING QTY:** |  |

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| --- | --- | --- | --- |
| **Point of Failure:** | Choose an item. | **Time to Failure:** |  |
| **Other Details:** | *[For Field failures, describe application, conditions, environment, etc. as applicable]**[For Reliability failures, describe test conditions, duration, sample size, etc. as applicable]* |

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| --- | --- | --- | --- |
| **FAILURE MODE:** | Choose an item. | **First Occurrence?** | [ ]  Yes [ ]  No |
| **Did replacing the defective device fix the problem?** | [ ]  Yes [ ]  No |
| **Any change in Design, Process or Application prior to failure?** | [ ]  Yes [ ]  No |
| **Has the failure been verified by a Semtech Field Applications Engineer?** | [ ]  Yes [ ]  No |
| **Failure Details:** | ***Insert failure information here, see examples below:**** *Failing channels and describe the channel configuration vs. Semtech product data sheet*
* *Specific register settings for the failing condition and full register dump if possible*
* *Description of troubleshooting results*
* *Output measurements and waveforms (good vs. bad) power up sequence, temperature testing sequence, applications schematics, etc.*
* *Test Equipment used (WFM, oscilloscope, BERT, etc. – indicate brand and model if applicable)*

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| **TEST CONDITIONS – Provide as many details as possible for more accurate FA** |
| **Supply Voltage:** |  | **Operating Mode (Rx/Tx, Loopback, etc.):** |  |
| **Input Level:** |  | **Configuration (single-ended or differential):**  |  |
| **Test Temp (0C):** |  | **Cable Length / Operating Range:** |  |
| **Data Rate:** |  | **Wavelength and Optical Power Level:** |  |
| **Data Pattern:** |  | **Communication Method (I2C, SPI, etc.):** |  |
| **BW or Frequency:** |  | **Firmware Revision:** |  |

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| **IMPORTANT NOTES*** **For bare die ICs**: Please return in an intact PCB whenever possible. Ensure that the die and bond wires are protected.
* **For optical modules**, please return an intact module whenever possible. Contact a Field Applications Engineer for additional requirements for module FA.
* **For incoming visual failures** related to mechanical damage or contamination, please provide photos as received and return in original Semtech packaging whenever possible.
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